Power MOSFET 60 V, 5.0 mΩ, 109 A, Single N–Channel

Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltag	V _{DSS}	60	V		
Gate-to-Source Voltage	Э		V _{GS}	±20	V
Continuous Drain Cur-		$T_{C} = 25^{\circ}C$	I _D	109	А
rent $R_{\theta JC}$ (Notes 1, 2, 3, 4)	Steady	T _C = 100°C		77	
Power Dissipation	State	$T_{C} = 25^{\circ}C$	PD	114	W
$R_{\theta JC}$ (Notes 1, 2, 3)		$T_{C} = 100^{\circ}C$		57	
Continuous Drain Cur-		T _A = 25°C	I _D	18	А
rent R _{θJA} (Notes 1 & 3, 4)	Steady State	$T_A = 100^{\circ}C$		15	
Power Dissipation		T _A = 25°C	PD	3.2	W
$R_{\theta JA}$ (Notes 1, 3)		T _A = 100°C		2.2	
Pulsed Drain Current	T _A = 25	°C, t _p = 10 μs	I _{DM}	440	А
Operating Junction and	T _J , T _{stg}	–55 to +175	°C		
Source Current (Body D	۱ _S	127	А		
Single Pulse Drain-to-S Energy (I _{L(pk)} = 5.0 A)	E _{AS}	142	mJ		
Lead Temperature for S (1/8" from case for 10 s	ΤL	260	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 3)	$R_{\theta JC}$	1.3	°C/W
Junction-to-Ambient - Steady State (Note 3)	R_{\thetaJA}	47	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

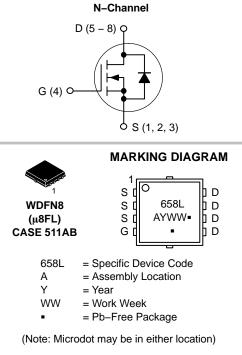
- 2. Psi (Ψ) is used as required per JESD51–12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



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V _{(BR)DSS} R _{DS(on)} MAX		I _D MAX
60 V	5.0 mΩ @ 10 V	109 A
	7.3 mΩ @ 4.5 V	109 A



ORDERING INFORMATION

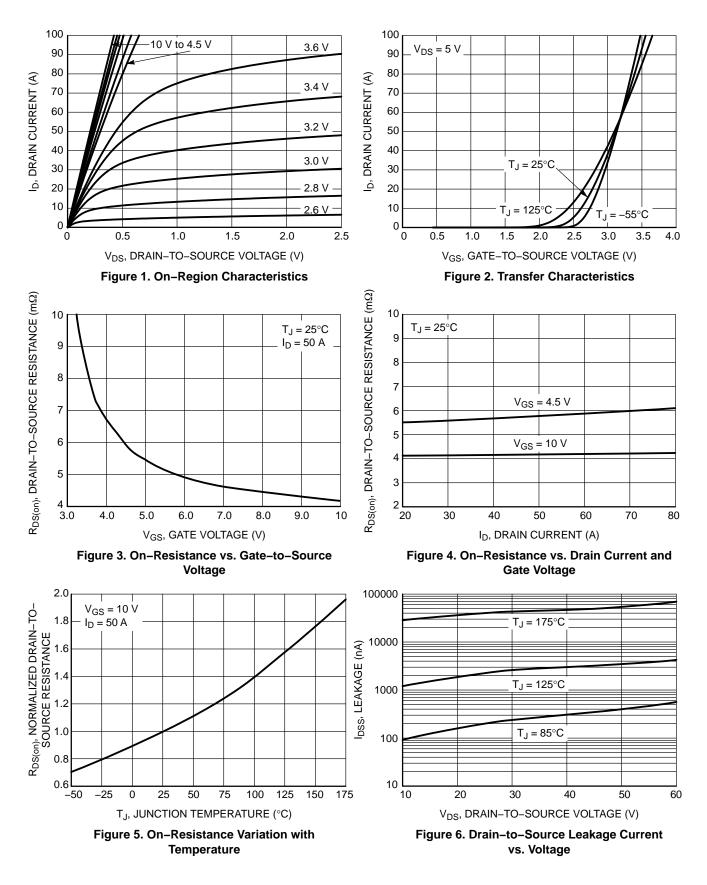
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

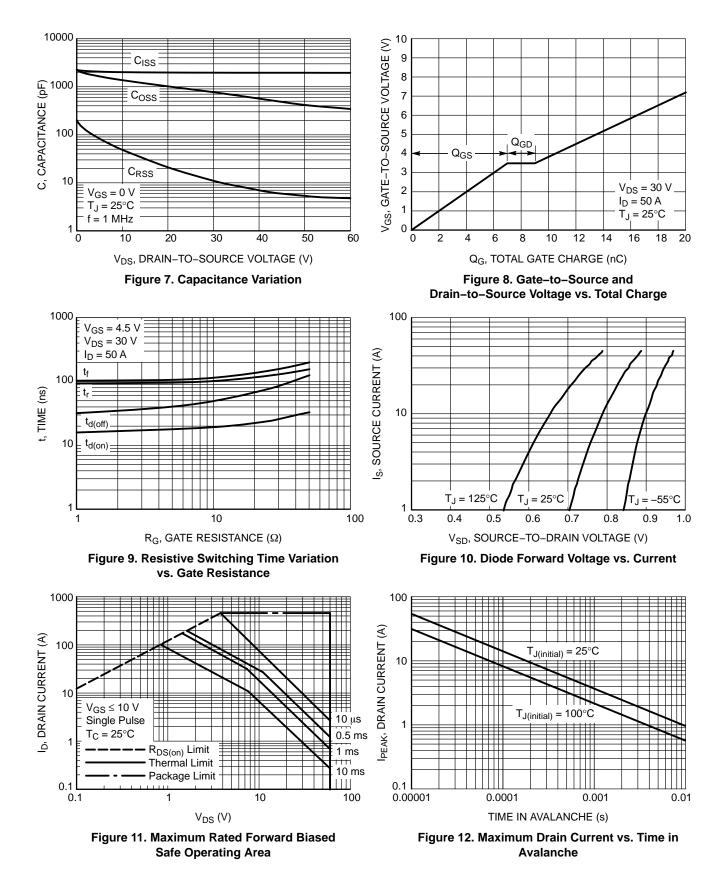
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	-	-			-	-	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I _D = 250 µA		60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$			10	μΑ
		$V_{DS} = 60 V$	$T_J = 125^{\circ}C$			250	1
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V	_{GS} = 20 V			100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{DS}$	₀ = 250 μA	1.2		2.2	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V,	I _D = 50 A		4.2	5.0	mΩ
		V _{GS} = 4.5 V,	I _D = 50 A		5.8	7.3	
Forward Transconductance	9 _{FS}	V _{DS} = 15 V,	I _D = 50 A		100		S
CHARGES AND CAPACITANCES							-
Input Capacitance	C _{iss}	V_{GS} = 0 V, f = 1.0 MHz, V_{DS} = 25 V			1935		pF
Output Capacitance	C _{oss}				890		
Reverse Transfer Capacitance	C _{rss}				16		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 30 V, I _D = 50 A			12		nC
Threshold Gate Charge	Q _{G(TH)}				3.5		nC
Gate-to-Source Charge	Q _{GS}				7		1
Gate-to-Drain Charge	Q _{GD}				2.4		1
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} =	30 V, I _D = 50 A		27		nC
SWITCHING CHARACTERISTICS (No	te 6)						-
Turn-On Delay Time	t _{d(on)}				16		ns
Rise Time	t _r	V _{GS} = 4.5 V. V	os = 30 V.		96		
Turn-Off Delay Time	t _{d(off)}	V _{GS} = 4.5 V, V I _D = 50	DĂ		36		
Fall Time	t _f	-	-		105		1
DRAIN-SOURCE DIODE CHARACTER	ISTICS	-			•		
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$		0.9	1.2	V
		I _S = 50 A	T _J = 125°C		0.8		1
Reverse Recovery Time	t _{RR}	1			39		ns
Charge Time	t _a	V_{GS} = 0 V, dl _S /dt = 100 A/µs, I _S = 50 A			21		1
Discharge Time	t _b				18		1
Reverse Recovery Charge	Q _{RR}				15		nC

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

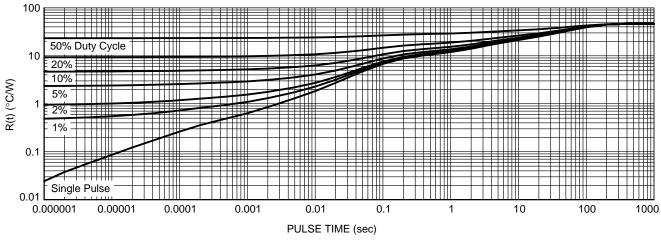


Figure 13. Thermal Characteristics

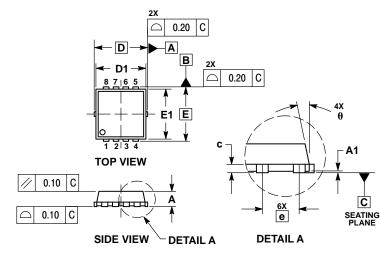
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTTFS5C658NLTAG	658L	WDFN8 (Pb–Free)	1500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

WDFN8 3.3x3.3, 0.65P CASE 511AB ISSUE D



С A 0.10 В ŧ 0.05 С e/2 4X E2 F3 м V D2 G-**BOTTOM VIEW**

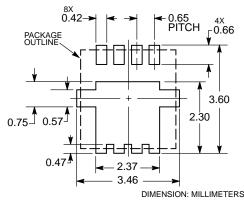


DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
CONTROLLING DIMENSION: MILLIMETERS.
DIMENSION DI AND E1 DO NOT INCLUDE MOLD FLASH

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PROTE	USIO	NS	OR (GAT	F BI	IR

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D		3.30 BSC		0.130 BSC			
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E	3.30 BSC			0.130 BSC			
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е	0.65 BSC			0.026 BSC			
G	0.30	0.41	0.51	0.012	0.016	0.020	
κ	0.65	0.80	0.95	0.026	0.032	0.037	
Г	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
м	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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